



## Product Specification

Product:	<b>Conductive Silver Paste</b>
Part Number:	<b>01M-4900 Series</b>

### Application Scope :

This product is suitable for use with tempered glass electrodes/heating.

### Usage Conditions :

Substrate	General glass tempering
Printing	200-300 mesh screen printing
Leveling	Let it level at room temperature for 5-15 minutes (adjust time based on actual leveling conditions).
Drying	Bake in a ventilation oven at 100-150°C for 10-15 minutes (the test temperature should not exceed 300°C; the baking time may be adjusted based on actual conditions).
Firing Condition	1. The sintering temperature is 600~750°C (recommended value) and the sintering time is 9-11 minutes. The sintering range can be adjusted between 600-800°C as needed. 2. Can be formed simultaneously with the glass fiber reinforced plastic (FRP) during tempering at 450-750°C
Thinner	ST-1000

### Characteristics:

Item	01M-4903	01M-4904	01M-4905	01M-4906	01M-4907	01M-4908	01M-4909
Fineness(um)	≤5	≤5	≤5	≤5	≤5	≤5	≤5
Viscosity (pa.s)	80-280	80-280	80-280	80-280	80-280	80-280	80-280
Silver content (%)	80~85	75~80	70~75	65~70	60~65	55~60	50~
Resistivity (mΩ/□)	≤3	≤5	≤7	≤10	≤15	≤20	≤30
Adhesion(N)	≥55	≥52	≥50	≥48	≥45	≥42	≥40



Standard	Test Method And Conditions
Fineness	FOG test
Viscosity	Brookfield HBT (Boli Fei) viscometer, rotor SC4-14/6R, 10 rpm, with adjustable viscosity at $25\pm1^{\circ}\text{C}$ according to user requirements.
Resistivity	The sintering film thickness is 8-12um. Test graph 0.6mm×60mm
Adhesion Strength	Peel Test: 0.5mm $\varphi$ Tin plated Cu wire soldered on 2mm×2mm Pad. Solder: 96.5Sn/0.5Cu Mildly activated flux used.

**Save Conditions And Validity Period :**

The product shall be stored in a sealed container at an ambient temperature of 5-25°C, with a shelf life of 1 year from the date of shipment.

**Packaging Method :**

Standard packaging, 1000g/can; samples are available in 200g small can packaging.